

SOT2025-1

FM8F, flange mount package, 6 terminals, 9.14 mm pitch,
32.255 mm x 9.96 mm x 3.81 mm body

10 August 2020

Package information

1 Package summary

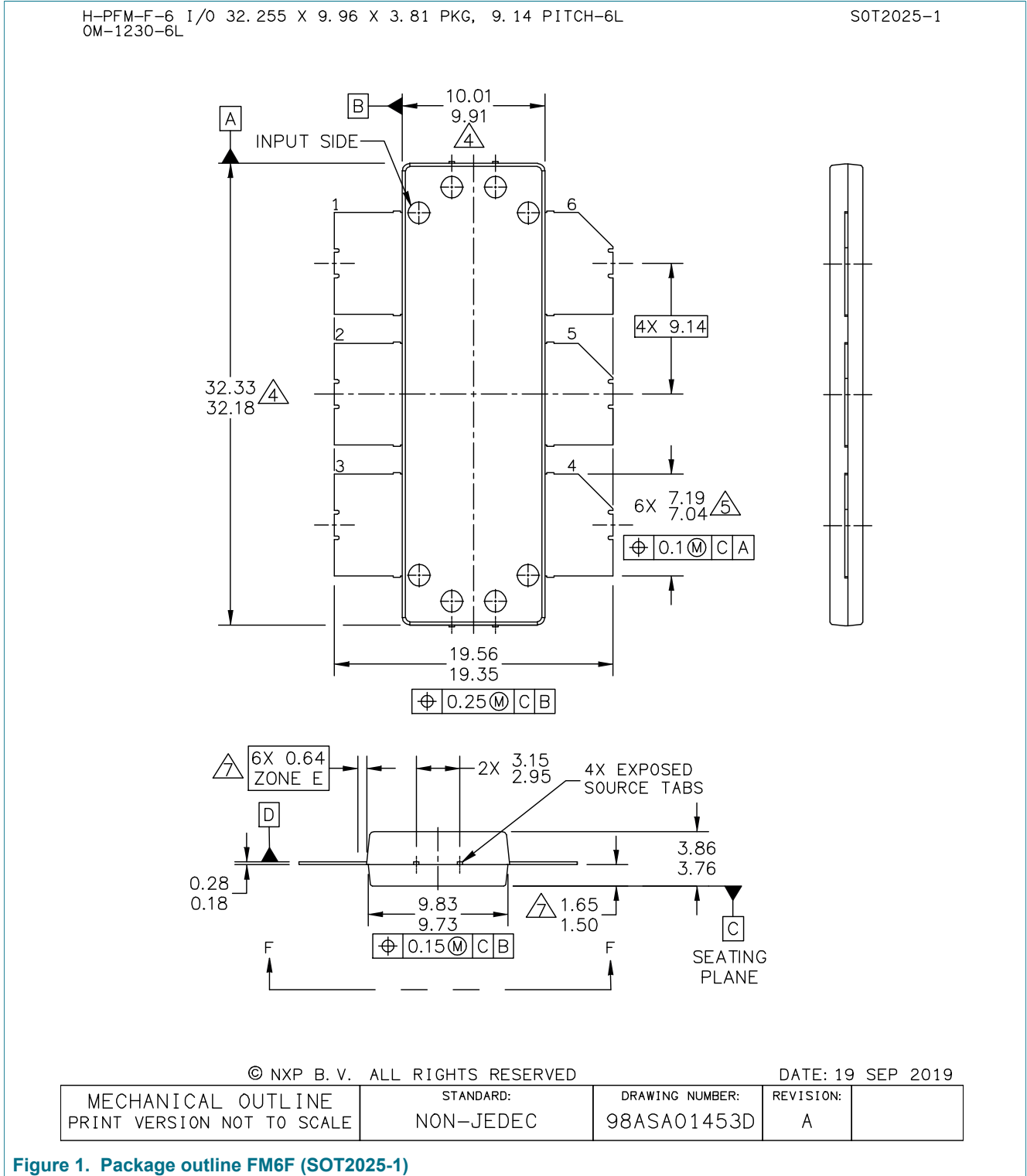
Terminal position code	P (perpendicular)
Package type descriptive code	FM6F
Package style descriptive code	DFM (double-ended flange mount)
Mounting method type	F (flange mount)
Issue date	19-09-2019
Manufacturer package code	98ASA01453D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	32.18	32.255	32.33	mm
package width	9.91	9.96	10.01	mm
package height	3.79	3.81	3.86	mm
nominal pitch	-	9.14	-	mm
actual quantity of termination	-	6	-	



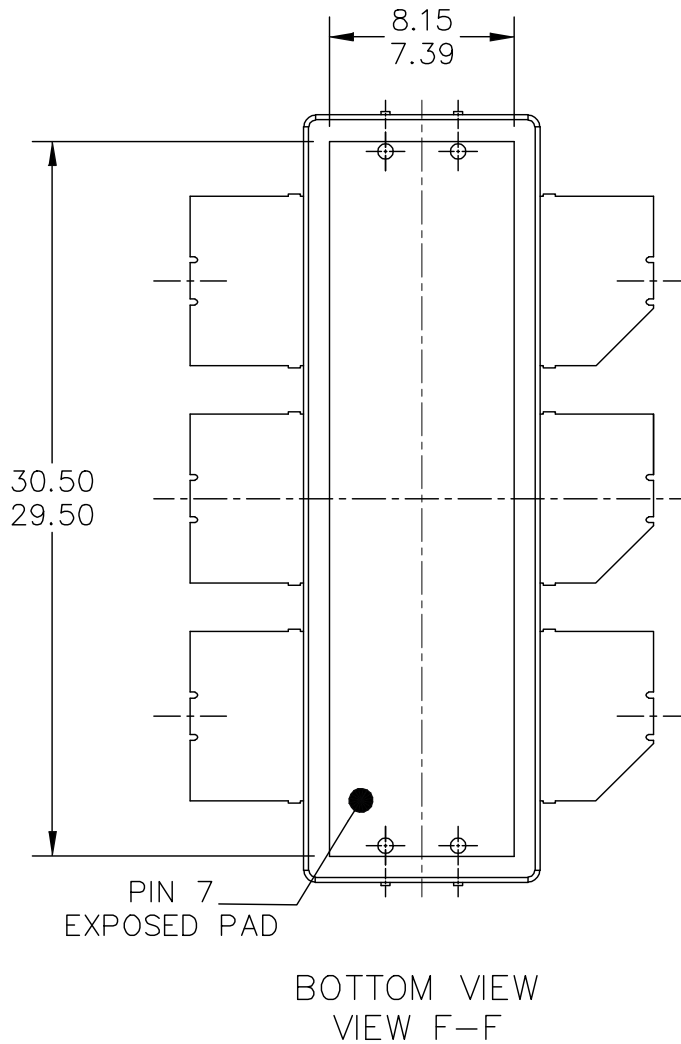
2 Package outline



FM8F, flange mount package, 6 terminals, 9.14 mm pitch, 32.255 mm x 9.96 mm x 3.81 mm body

H-PFM-F-6 I/O 32.255 X 9.96 X 3.81 PKG, 9.14 PITCH-6L
OM-1230-6L

SOT2025-1



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


Figure 2. Package outline detail of FM6F (SOT2025-1)

FM8F, flange mount package, 6 terminals, 9.14 mm pitch, 32.255 mm x 9.96 mm x 3.81 mm body

H-PFM-F-6 I/O 32.255 X 9.96 X 3.81 PKG, 9.14 PITCH-6L
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NOTES:

1. CONTROLLING DIMENSION: MILLIMETER
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE D IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4.  DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.15 MM PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE D.
5.  DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 MM TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE D.
7.  DIMENSION APPLIES WITHIN ZONE E ONLY.

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Figure 3. Package outline note FM6F (SOT2025-1)

3 Legal information

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